

iC-LF1401 OLGA LF2C

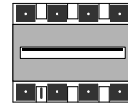
PACKAGE SPECIFICATION



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ORDERING INFORMATION

Type	Package	Options	Order Designation
iC-LF1401	OLGA LF2C	none	iC-LF OLGA LF2C

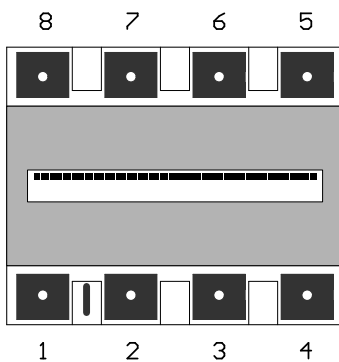


9.7 mm x 8.0 mm

PIN CONFIGURATION

PIN FUNCTIONS

(top view)



No.	Name	Function
1	SI	Start Integration Input
2	CLK	Clock Input
3	AO	Analogue Output
4	VCC	+5 V Supply Voltage
5	RSET	Bias Current Adjust
6	AGND	Analog Ground
7	GND	Digital Ground
8	DIS	Disable Integration Input

ABSOLUTE MAXIMUM RATINGS

Item No.	Symbol	Parameter	Conditions	Fig.	Min.	Typ.	Max.	Unit
TG1	Ta	Operating Ambient Temperature Range (extended temperature range on request)			-40		100	°C
TG2	Ts	Storage Temperature Range			-40		115	°C
TG3	Tpk	Reflow Soldering Peak Temperature	tpk < 20 s, convection reflow tpk < 20 s, vapour phase TOL (time on label) 8 h; please refer to Customer Information #7 for details				245 230	°C °C

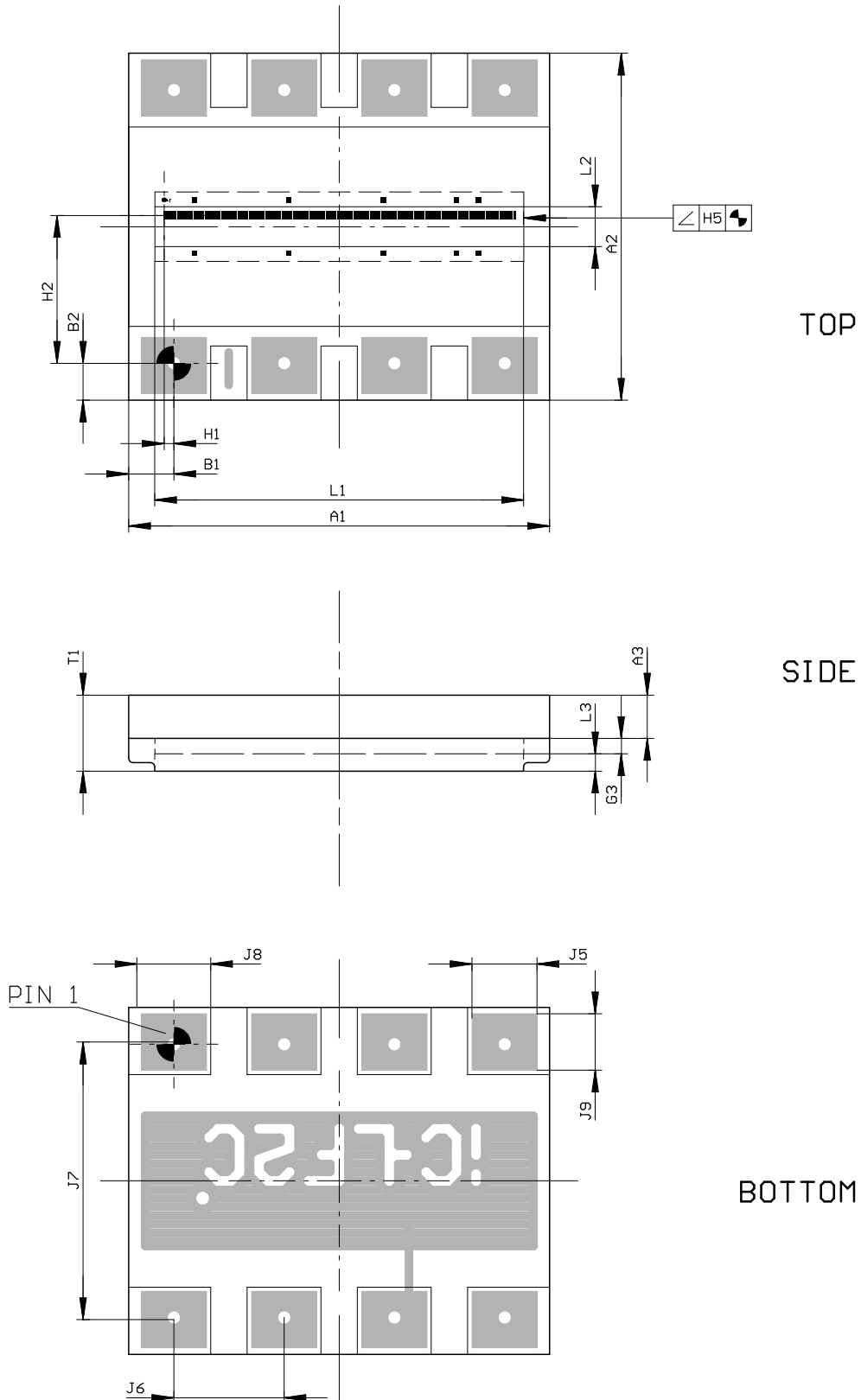
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PHYSICAL DIMENSIONS



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DIMENSION TABLE

Item	Parameter	Comments					Unit
			Min.	Typ.	Max.	Tolerance	
Substrate							
A1	Outline X			9.7		±0.1	mm
A2	Outline Y			8.0		±0.15	mm
A3	Substrate Thickness	bottom package to bottom die	0.917	1.0	1.27		mm
Reference							
(B1)	Outline vs. Reference X	bottom left lead center is reference		1.04		±0.1	mm
(B2)	Outline vs. Reference Y	bottom left lead center is reference		0.85		±0.1	mm
Chip Placement							
G3	Chip Thickness			0.3		±0.025	mm
H1	Chip Position vs. Reference X	reference vs. center of 1 st sensor		0.223		±0.15	mm
H2	Chip Position vs. Reference Y	reference vs. center of 1 st sensor		3.409		±0.15	mm
H5	Chip Tilt Angle vs. Paddle					±1.6	DEG
Bottom Metal Pattern							
J5	Lead Size X			1.5		±0.03	mm
J6	Lead Pitch X (or Lead-Lead Distance X)			2.54			mm
J7	Lead Pitch Y (or Lead-Lead Distance Y)	Mid of lead (not drill; drill is not center of lead)		6.4			mm
J8	Solder Stop Off			1.7		±0.1	mm
J9	Lead Size Y			1.3		±0.03	mm
Encapulant (Glass Cover)							
L1	Glass Size X			8.5		±0.05	mm
L2	Glass Size Y			0.92		±0.05	mm
L3	Glass Thickness			0.4		±0.03	mm
Thickness Specifications							
T1	Overall Thickness		1.56		2.0		mm

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REVISION HISTORY

Rev	Notes	Pages affected
A1	Initial version	
B1	Substrate length shortened to 9.7 mm, smaller tolerance	all
B2	Paddle/shield connected to AGND (was GND); General Handling Instruction updated	all
C1	RoHS compliance	1, 4
D1	Convection reflow soldering peak temperature reduced to 245 °C	1, 4

GENERAL HANDLING INSTRUCTIONS

After opening the dry pack, devices must be mounted within 8 hours (in factory conditions of maximum 30 °C/60% RH) or must be stored at < 10% RH. Devices require baking before mounting if the Humidity

Indicator Card shows > 10% when read at 23 °C ±5 °C or if the conditions mentioned above are not met. Devices may be baked for 72 hours at 100 °C using high-temperature device containers (trays).

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